IPC-9121-AM2

Troubleshooting for Printed Board Fabrication Processes

Amendment 2

Developed by the Printed Board Process Effects Handbook Subcommittee (7-24) of the Process Control Management Committee (7-20) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

Contact:

IPC

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New documents for Section 2 Applicable Documents

2.1 IPC

IPC-TM-650, Test Methods Manual

2.6.7.2 Thermal Shock, Continuity and Microsection, Printed Board

2.6.26 DC Current Induced Thermal Cycling Test

2.6.27 Thermal Stress, Convection Reflow Assembly Simulation

IPC-4552 Performance Specification for Electroless Nickel/Immersion Gold (ENIG) Plating for Printed Boards

New topics for Section 6 Mechanical Operations

6.1.2 Hole Quality

Issue: Debris in Back-Drill Hole

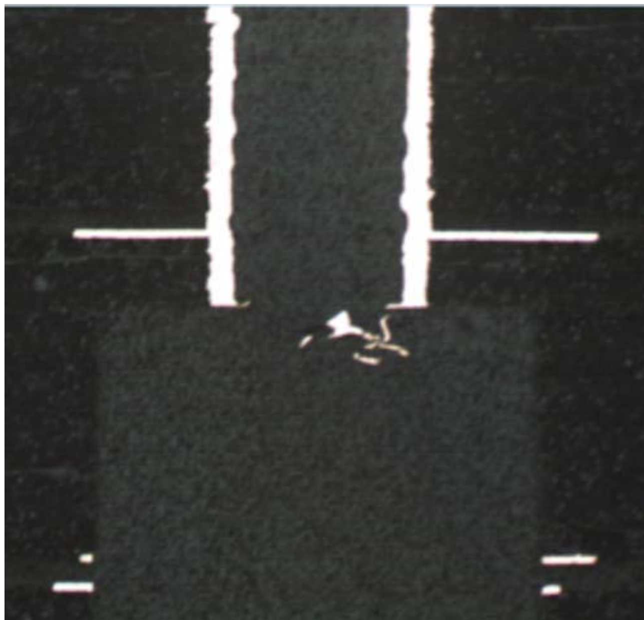

Figure 6.1.2-7

CAUSE	**ACTION**
Drill parameters not optimized	Optimize drill parameters
Potential test method (discover)	**Potential test method (verification)**
Microscope inspection after back-drill	